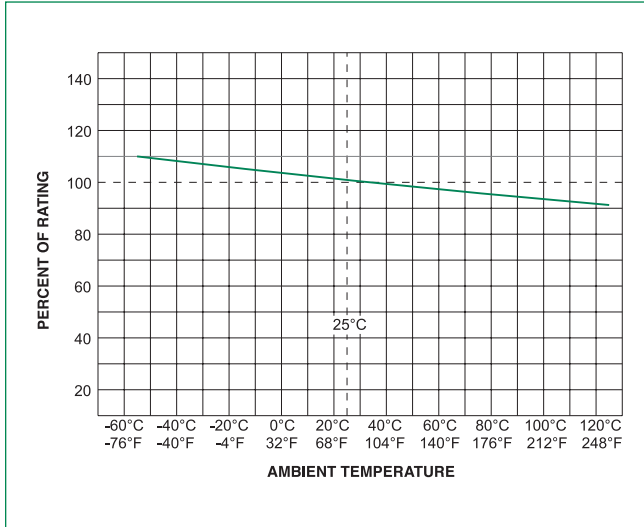


**Temperature Re-rating Curve**



**Note:**  
 Rerating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

**Soldering Parameters**

**Recommended Process Parameters:**

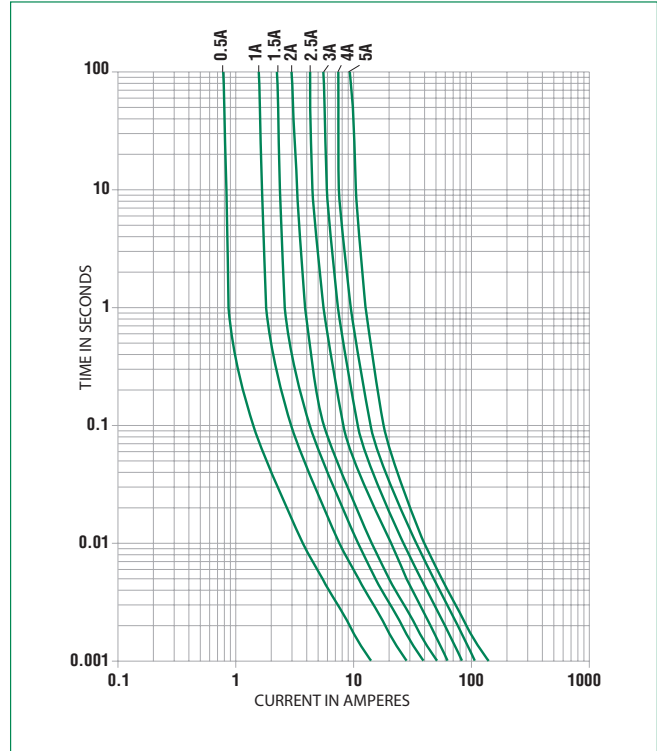
Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum:	100°C
Temperature Maximum:	150°C
Preheat Time:	60-180 seconds
Solder Pot Temperature:	260°C Maximum
Solder Dwell Time:	2-5 seconds

**Recommended Hand-Solder Parameters:**

Solder Iron Temperature: 350°C +/- 5°C  
 Heating Time: 5 seconds max.

**Note:** These devices are not recommended for IR or Convection Reflow process.

**Average Time Current Curves**

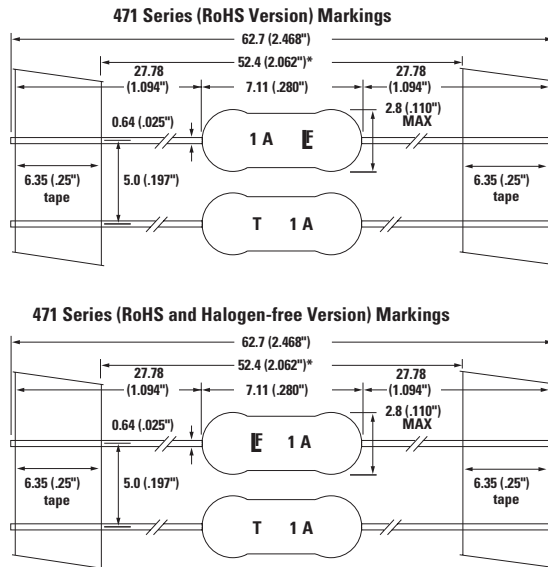


### Product Characteristics

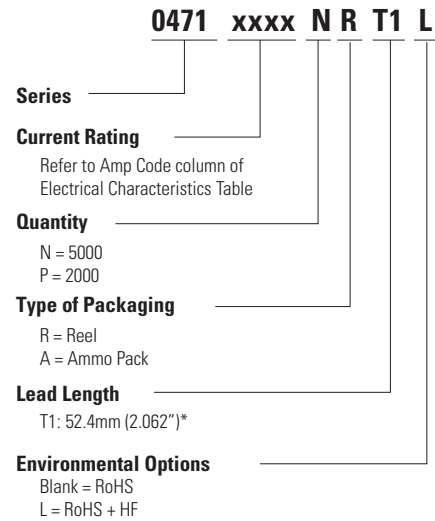
<b>Materials</b>	Encapsulated, Epoxy-Coated Body; Solder Coated Copper wire leads; RoHS compliant Product: Pure Tin-coated Copper wire leads
<b>Flammability Rating</b>	UL 94V-0
<b>Solderability</b>	MIL-STD-202, Method 208
<b>Lead Pull Force</b>	MIL-STD-202, Method 211, Test Condition A (will withstand a 7 lbs. axial pull test)

<b>Operating Temperature</b>	-55°C to +125°C (Consider re-rating)
<b>Shock</b>	MIL-STD-202, Method 213, Test Condition I (100 G's peak for 6 milliseconds)
<b>Vibration</b>	MIL-STD-202, Method 201 (10-55 Hz); Method 204, Test Condition C (55-2000 Hz at 10 G's Peak)
<b>Moisture Resistance</b>	MIL-STD-202, Method 106
<b>Resistance to Soldering Heat</b>	Withstands 60 seconds above 200°C and up to 260°C, maximum

### Dimensions



### Part Numbering System



### Packaging

Packaging Option	Packaging Specification	Quantity & Packaging Code
*T1: 52.4mm (2.062") Tape and Reel	EIA 296	Please refer to available quantities above in "Part Numbering System"

**Notes:** \* T1 dimension is defined as the length of the component between the two tapes. The full component length is 62.7mm (2.468").